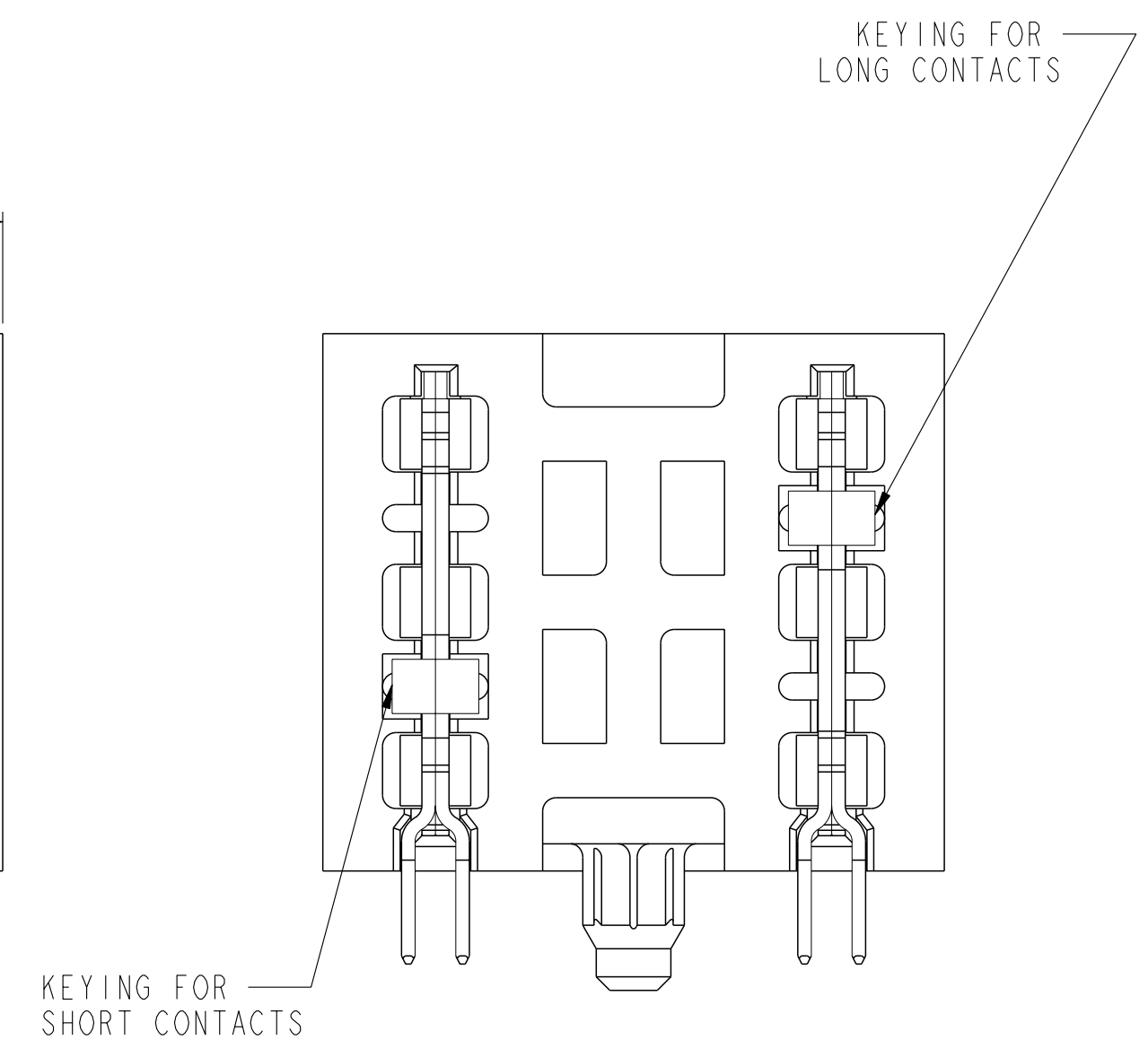
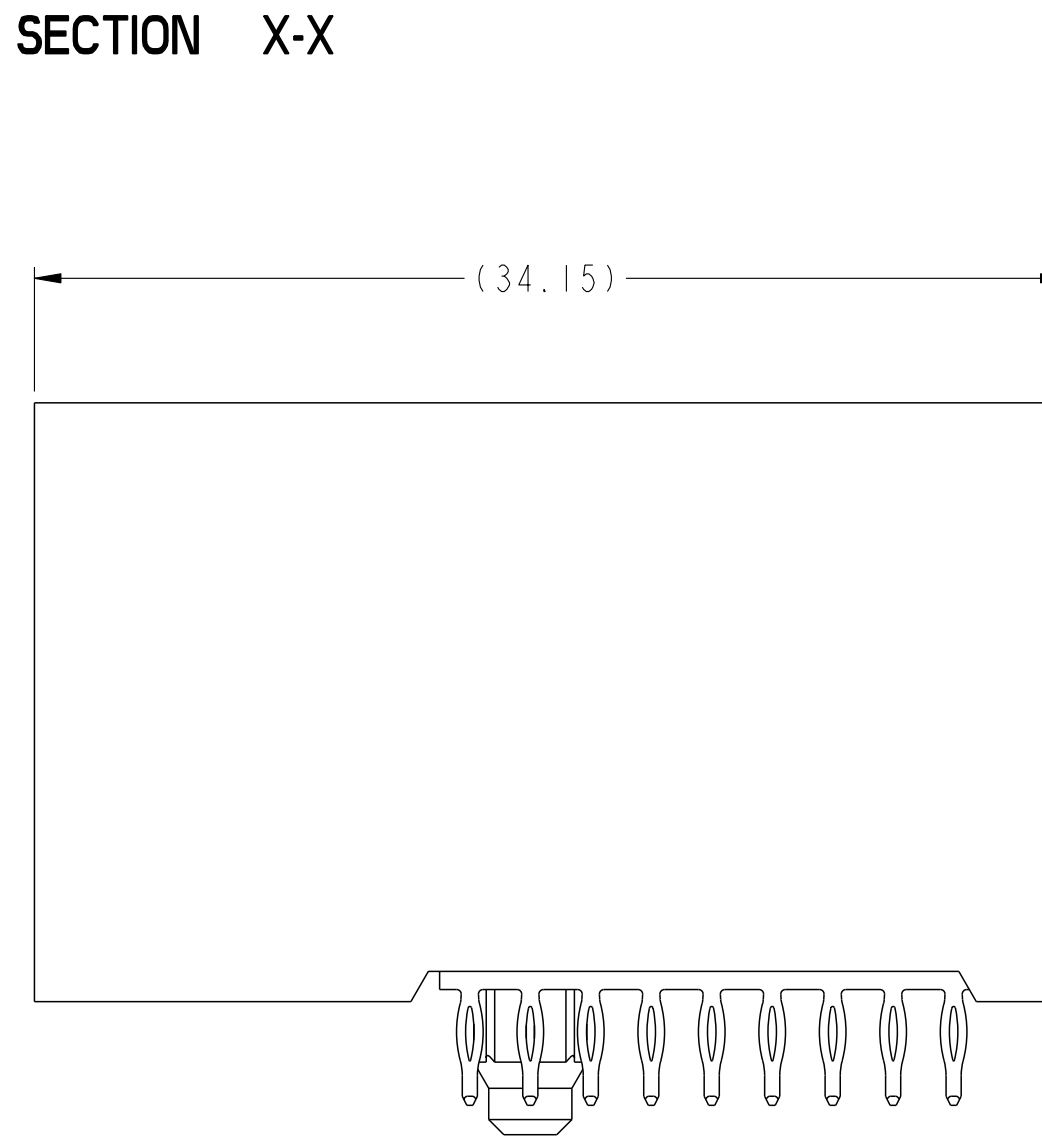
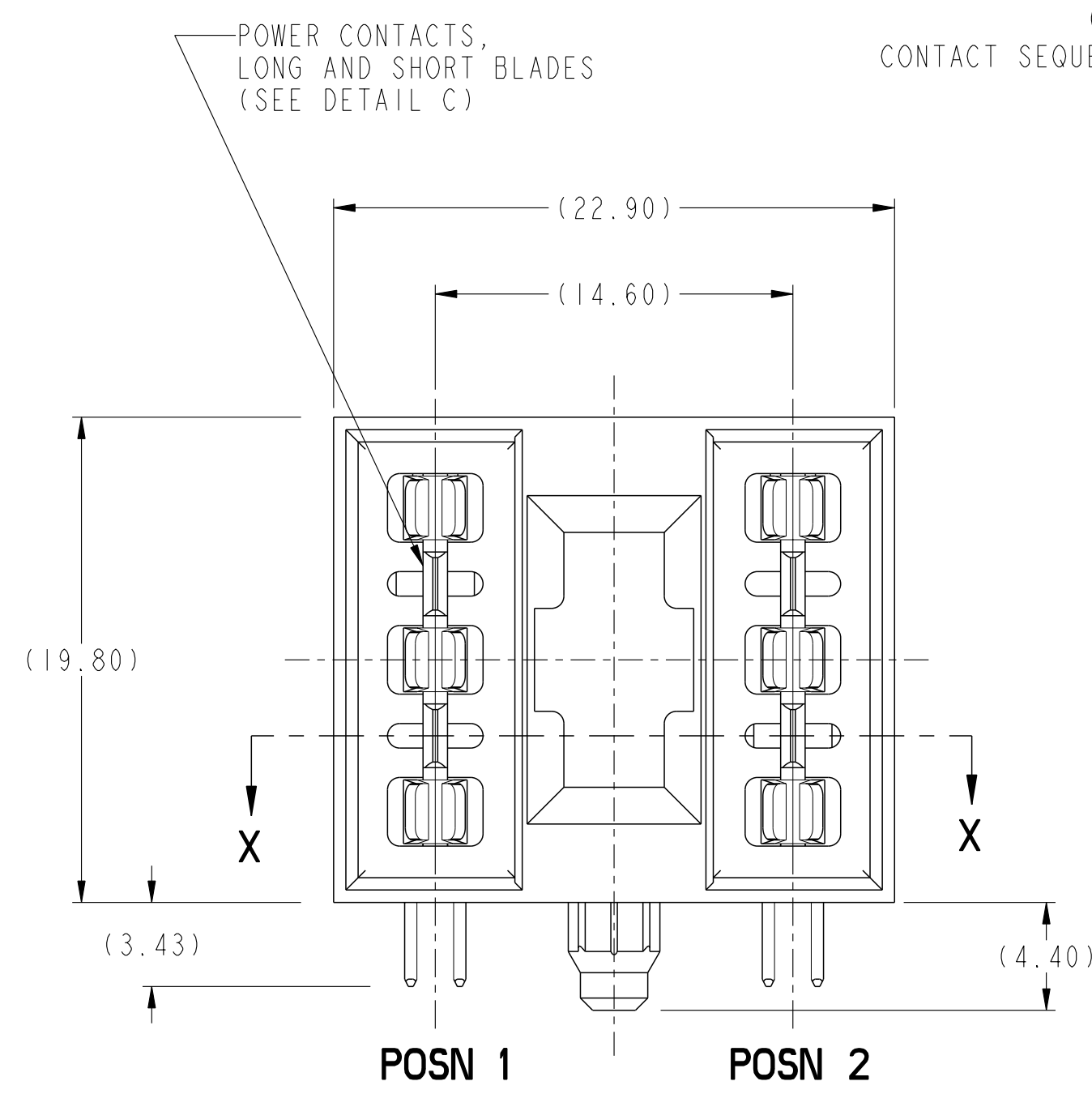
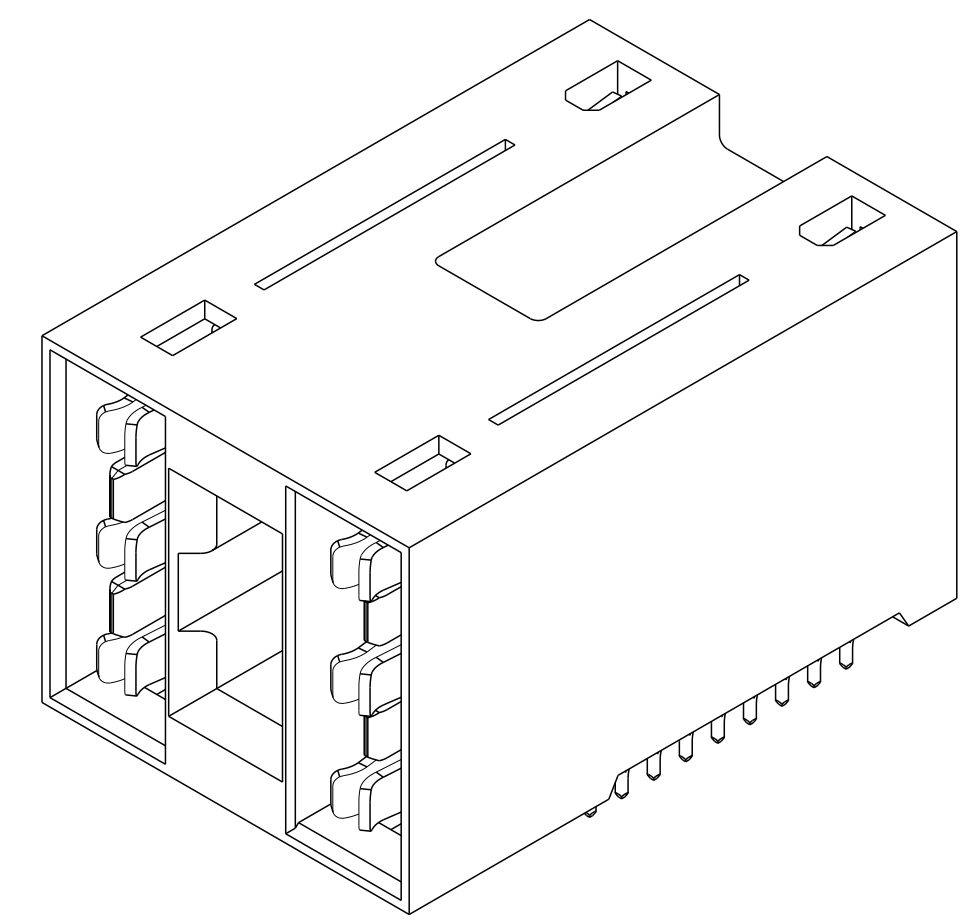
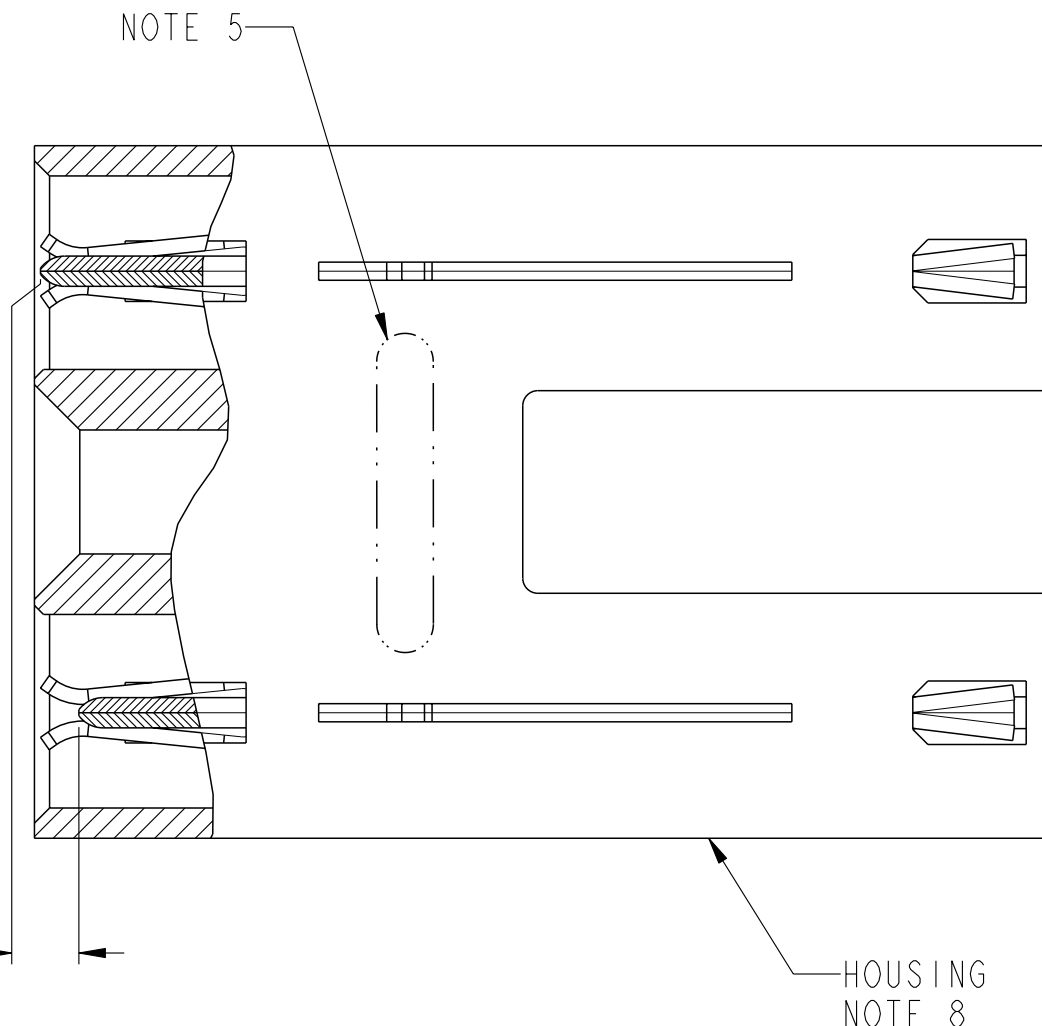


PART NUMBER	FIRST MATE (LONG) CONTACT POSN	SECOND MATE (SHORT) CONTACT POSN	TAIL TYPE
I0087937-001LF	NONE	POSN 1 & 2	PRESS-FIT
I0087937-002LF	POSN 1	POSN 2	



10087937-002 SHOWN

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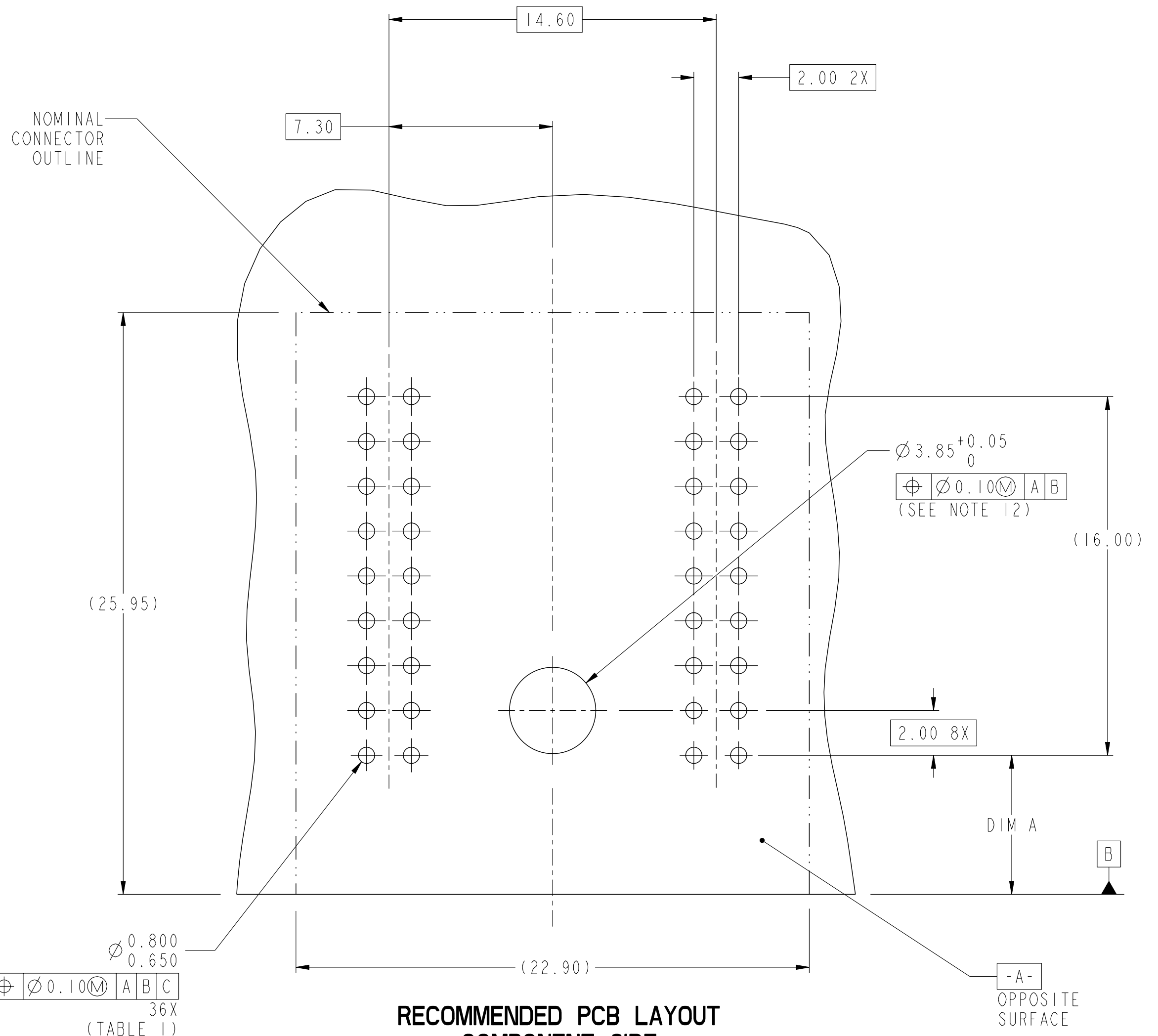
rev	ecn no	dr	date
A	V09-0207	TH	2009-04-29
B	V09-0213	TH	2009-05-04
-	-	-	-
-	-	-	-
-	-	-	-
-	-	-	-

www.fciconnect.com		surface ASME Y14.5	tolerance std ASME Y14.5	projection ASME Y14.5	MM
		TOLERANCES UNLESS OTHERWISE SPECIFIED			
Dr	T.HOUTZ	2008-04-25	ANGULAR	0.X	±.3
Eng	H.NGO	2008-04-25	LINEAR	0.XX	±.10
Chr	H.NGO	2008-04-25	0° ±2°	0.XXX	±.050
Appr	H.NGO	2008-04-25	Product family	HCI	Spec ref
FCI		TITLE ASSEMBLY, HEADER, R/A, 2 POSN BACKPANEL MODULE W/GUIDE		catlog no	10087937
		CUSTOMER		sheet 1 of 2	Rev. B

TOP LAYER DESCRIPTION	TABLE 1 (HCI POWER) PLATED THROUGH-HOLE REQUIREMENTS							
	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	TIN THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETER
TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	--	--	--	0.65 - 0.80
IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	0.9 - 1.5um	--	0.70 - 0.80
IMMERSION SILVER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	0.15 - 0.65um	0.70 - 0.80
COPPER (SEE NOTE 9)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	--	--	--	0.70 - 0.80
GOLD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.003 - 0.007	FLASH UP TO 0.0002	--	--	0.69 - 0.80

NOTES:

- CONNECTOR MATERIALS:
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK
UL 94V-0 COMPLIANT
CONTACTS: HIGH PERFORMANCE COPPER ALLOY
- CONTACT FINISH (Ref. GS-12-380 SECTION 5.2)
- PRODUCT SPECIFICATION: GS-12-380.
- APPLICATION SPECIFICATION: GS-20-070.
- PRODUCT MARKING (PRODUCT NUMBER & DATE CODE) ON HOUSING IN AREA SHOWN.
- MINIMUM NOMINAL PCB THICKNESS: 1.6mm
- PACKAGING MEETS FCI SPECIFICATION GS-14-1194
- HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
- COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.
- ALL HOLE SIZES ARE FINISHED HOLE SIZES UNLESS OTHERWISE NOTED.
- THE GUIDANCE SYSTEM OF THIS PRODUCT IS INTENDED TO PROVIDE DAUGHTER CARD ALIGNMENT WITH RESPECT TO THE SYSTEM BACKPLANE OR MIDPLANE. HOWEVER, FACTORS SUCH AS THE DAUGHTER CARD SIZE AND WEIGHT, THE OVERALL SYSTEM CARD GUIDE DESIGN, ETC SHOULD BE CONSIDERED WHEN DECIDING WHETHER ADDITIONAL EXTERNAL GUIDE HARDWARE IS NEEDED.
- UNPLATED HOLES.



DIM A	DISTANCE FROM BOARD TO BOARD AT FULLY MATED POSITION (NOMINAL)	PRODUCT LINE APPLICATION
8.70 mm	10.0 mm	Metral High Speed
6.20 mm	12.5 mm (H.M.)	Airmax VS,Zipline
2.20 mm	16.5 mm	XCede

**RECOMMENDED PCB LAYOUT
COMPONENT SIDE
NOTE 6**

	TITLE ASSEMBLY, HEADER, R/A, 2 POSN BACKPANEL MODULE W/GUIDE	dwg no 10087937	Rev. B
	catalog no	CUSTOMER	sheet 2 of 2

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REV F - 2006-04-17